

FORM PTO-1449 U. S. DEPARTMENT OF COMMERCE
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U 015850-2

10/542,123

INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

(Use several sheets if necessary)

APPLICANT

Vladimir Pavlovich POPOV et al.

FILING DATE

GROUP

December 9, 2005

2817 2823

U.S. PATENT DOCUMENTS

EXAMINER INITIALS	REFERENCE DESIGNATION	DOCUMENT NUMBER	DATE	NAME	FILING DATE IF APPROPRIATE
	AA				
	AB				
	AC				

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
					YES	NO
	AD					
	AE					
	AF					

OTHER ART (Including Author, Title, Date, Pertinent Dates, Etc.)

QJ	AG	Rieutord, F. et al. "Dynamics of a Bonding Front" <i>Physical Review Letters</i> (2005) PRL Vol. 94
QJ	AH	Takahagi, T. et al. "Adsorbed Water on a Silicon Wafer Surface Exposed to Atmosphere" <i>Jpn. J. Appl. Phys.</i> (2001) Vol. 40, No. 11, Part 1, pp 6198-6201
QJ	AI	Gosele, U. et al. "Self-Propagating Room-Temperature Silicon Wafer Bonding in Ultrahigh Vacuum" <i>Appl. Phys. Lett.</i> (1995) Vol. 67, No. 24, pp 3614-3616
QJ	AJ	Farrens, S.N. et al. "Chemical Free Room Temperature Wafer to Wafer Direct Bonding" <i>J. Electrochem. Soc.</i> (1995) Vol. 142, No. 11, pp 3949-3955
QJ	AK	Tong, Q. Y. et al. "Low Vacuum Wafer Bonding" <i>Electrochemical and Solid-State Letters</i> (1998) Vol. 1, No. 1, pp 52-53
QJ	AL	Tong, Q. Y. et al. "Semiconductor Wafer Bonding: Science and Technology" <i>John Wiley & Sons, Inc.</i> (1999) pp 52-53, and pp 122-127
QJ	AM	Esser, R. H. et al. "Improved Low-Temperature Si-Si Hydrophilic Wafer Bonding" <i>Journal of the Electrochemical Society</i> (2003) Vol. 150, No. 3, G228-G231
QJ	AN	Dragoi, V. et al. "Plasma Activated Wafer Bonding for MEMS" <i>SPIE Proceeding</i> 5836 (2005) paper no. 5836-19
QJ	AO	"Long-Term Stability of Vacuum-Encapsulated MEMS Devices Using Eutectic Wafer Bonding" <i>VABOND-Deliverable 6.4 - Technology Guidelines on Vacuum Encapsulation of MEMS</i>
QJ	AP	Zhang, X. et al. "Low-Temperature Wafer Bonding Optimal O ₂ Plasma Surface Pretreatment Time" <i>Electrochemical and Solid-State Letters</i> (2004) Vol. 7, No. 8, G172-G174

EXAMINER

/Quovaunda Jefferson/

DATE CONSIDERED 01/11/2007

EXAMINER:

Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.